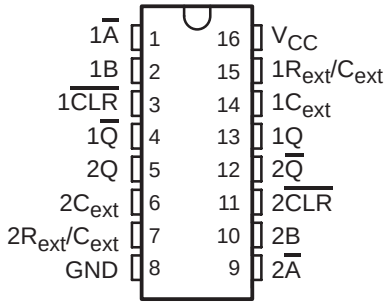
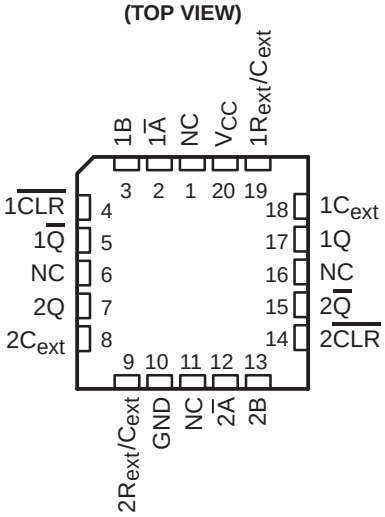
- **2-V to 5.5-V V_{CC} Operation**
- **Max t_{pd} of 11 ns at 5 V**
- **Support Mixed-Mode Voltage Operation on All Ports**
- **Schmitt-Trigger Circuitry on $\overline{A}$, B, and $\overline{CLR}$ Inputs for Slow Input Transition Rates**
- **Overriding Clear Terminates Output Pulse**
- **Glitch-Free Power-Up Reset on Outputs**
- **I_{off} Supports Partial-Power-Down Mode Operation**
- **Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II**
- **ESD Protection Exceeds JESD 22**
  - **2000-V Human-Body Model (A114-A)**
  - **200-V Machine Model (A115-A)**
  - **1000-V Charged-Device Model (C101)**

SN54LV221A . . . J OR W PACKAGE
SN74LV221A . . . D, DB, DGV, NS, OR PW PACKAGE
(TOP VIEW)



SN54LV221A . . . FK PACKAGE
(TOP VIEW)



NC − No internal connection

description/ordering information

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
−40°C to 85°C	SOIC − D	Tube of 40	SN74LV221AD	LV221A
		Reel of 2500	SN74LV221ADR	
	SOP − NS	Reel of 2000	SN74LV221ANSR	74LV221A
	SSOP − DB	Reel of 2000	SN74LV221ADBR	LV221A
	TSSOP − PW	Tube of 90	SN74LV221APW	LV221A
		Reel of 2000	SN74LV221APWR	
		Reel of 250	SN74LV221APWT	
	TVSOP − DGV	Reel of 2000	SN74LV221ADGVR	LV221A
−55°C to 125°C	CDIP − J	Tube of 25	SNJ54LV221AJ	SNJ54LV221AJ
	CFP − W	Tube of 150	SNJ54LV221AW	SNJ54LV221AW
	LCCC − FK	Tube of 55	SNJ54LV221AFK	SNJ54LV221AFK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

description/ordering information (continued)

The ’LV221A devices are dual multivibrators designed for 2-V to 5.5-V V_{CC} operation. Each multivibrator has a negative-transition-triggered ($\overline{A}$) input and a positive-transition-triggered (B) input, either of which can be used as an inhibit input.

These edge-triggered multivibrators feature output pulse-duration control by three methods. In the first method, the $\overline{A}$ input is low and the B input goes high. In the second method, the B input is high and the $\overline{A}$ input goes low. In the third method, the $\overline{A}$ input is low, the B input is high, and the clear ($\overline{CLR}$) input goes high.

The output pulse duration is programmable by selecting external resistance and capacitance values. The external timing capacitor must be connected between C_{ext} and R_{ext}/C_{ext}(positive) and an external resistor connected between R_{ext}/C_{ext} and V_{CC}. To obtain variable pulse durations, connect an external variable resistor between R_{ext}/C_{ext} and V_{CC}. The output pulse duration also can be reduced by taking $\overline{CLR}$ low.

Pulse triggering occurs at a particular voltage level and is not related directly to the transition time of the input pulse. The $\overline{A}$, B, and $\overline{CLR}$ inputs have Schmitt triggers with sufficient hysteresis to handle slow input transition rates with jitter-free triggering at the outputs.

Once triggered, the outputs are independent of further transitions of the $\overline{A}$ and B inputs and are a function of the timing components, or the output pulses can be terminated by the overriding clear. Input pulses can be of any duration relative to the output pulse. Output pulse duration can be varied by choosing the appropriate timing components. Output rise and fall times are TTL compatible and independent of pulse duration. Typical triggering and clearing sequences are illustrated in the input/output timing diagram.

The variance in output pulse duration from device to device typically is less than ±0.5% for given external timing components. An example of this distribution for the ’LV221A is shown in Figure 8. Variations in output pulse duration versus supply voltage and temperature are shown in Figure 5.

During power up, Q outputs are in the low state, and $\overline{Q}$ outputs are in the high state. The outputs are glitch free, without applying a reset pulse.

These devices are fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

Pin assignments are identical to those of the ’AHC123A and ’AHCT123A devices, so the ’LV221A can be substituted for those devices not using the retrigger feature.

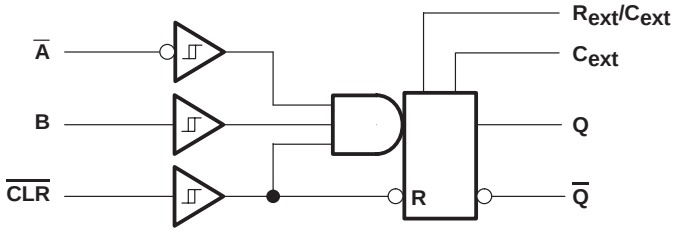
For additional application information on multivibrators, see the application report *Designing With The SN74AHC123A and SN74AHCT123A*, literature number SCLA014.

FUNCTION TABLE
(each multivibrator)

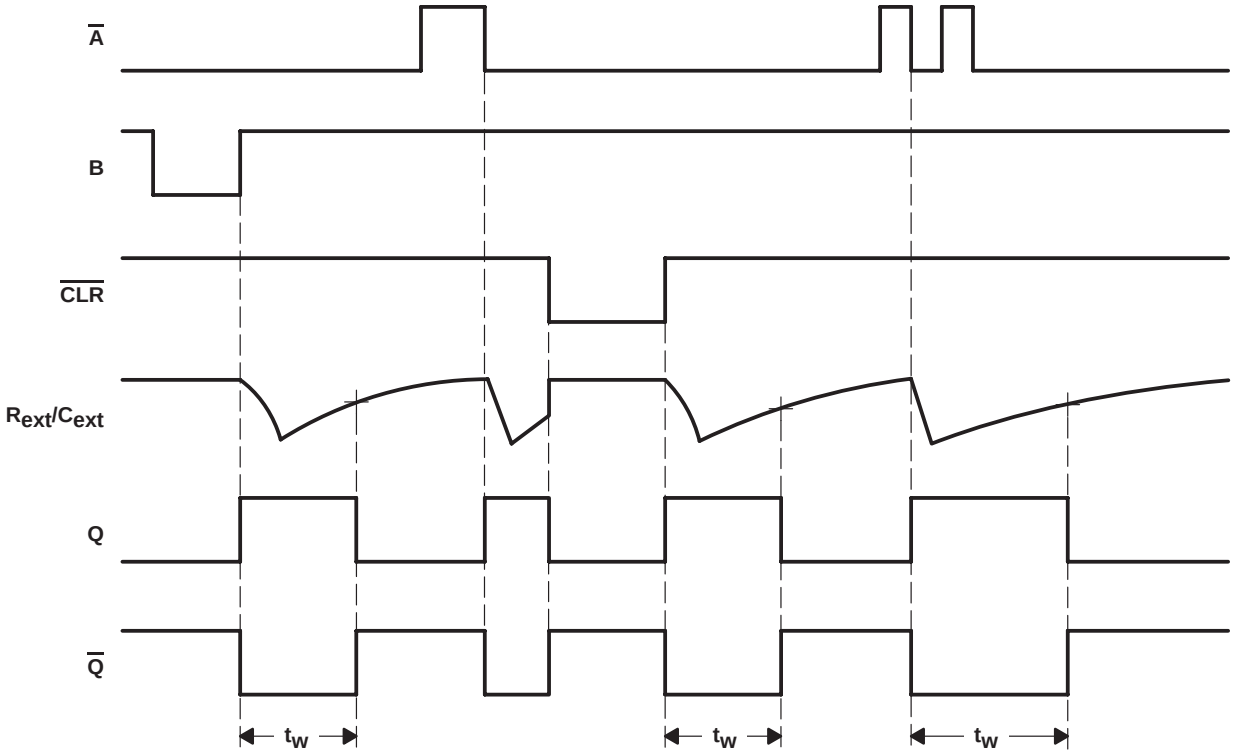
INPUTS			OUTPUTS		FUNCTION
$\overline{CLR}$	$\overline{A}$	B	Q	$\overline{Q}$	
L	X	X	L	H	Reset
H	H	X	L	H	Inhibit
H	X	L	L	H	Inhibit
H	L	↑	⎍	⎎	Outputs enabled
H	↓	H	⎍	⎎	Outputs enabled
↑†	L	H	⎍	⎎	Outputs enabled

† This condition is true only if the output of the latch formed by the NAND gate has been conditioned to the logic 1 state prior to $\overline{CLR}$ going high. This latch is conditioned by taking either $\overline{A}$ high or B low while $\overline{CLR}$ is inactive (high).

logic diagram, each multivibrator (positive logic)



input/output timing diagram



absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage range, V_{CC}	−0.5 V to 7 V
Input voltage range, V_I (see Note 1)	−0.5 V to 7 V
Output voltage range in high or low state, V_O (see Notes 1 and 2)	−0.5 V to V_{CC} + 0.5 V
Output voltage range in power-off state, V_O (see Note 1)	−0.5 V to 7 V
Input clamp current, I_{IK} (V_I < 0)	−20 mA
Output clamp current, I_{OK} (V_O < 0)	−50 mA
Continuous output current, I_O (V_O = 0 to V_{CC})	±25 mA
Continuous current through V_{CC} or GND	±50 mA
Package thermal impedance, θ_{JA} (see Note 3): D package	73°C/W
DB package	82°C/W
DGV package	120°C/W
NS package	64°C/W
PW package	108°C/W
Storage temperature range, T_{stg}	−65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
2. This value is limited to 5.5 V maximum.
3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4)

			SN54LV221A		SN74LV221A		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	5.5	2	5.5	V
V_{IH}	High-level input voltage	V_{CC} = 2 V	1.5		1.5		V
		V_{CC} = 2.3 V to 2.7 V	$V_{CC} \times 0.7$		$V_{CC} \times 0.7$		
		V_{CC} = 3 V to 3.6 V	$V_{CC} \times 0.7$		$V_{CC} \times 0.7$		
		V_{CC} = 4.5 V to 5.5 V	$V_{CC} \times 0.7$		$V_{CC} \times 0.7$		
V_{IL}	Low-level input voltage	V_{CC} = 2 V		0.5		0.5	V
		V_{CC} = 2.3 V to 2.7 V		$V_{CC} \times 0.3$		$V_{CC} \times 0.3$	
		V_{CC} = 3 V to 3.6 V		$V_{CC} \times 0.3$		$V_{CC} \times 0.3$	
		V_{CC} = 4.5 V to 5.5 V		$V_{CC} \times 0.3$		$V_{CC} \times 0.3$	
V_I	Input voltage		0	5.5	0	5.5	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 2 V		−50		−50	μA
		V_{CC} = 2.3 V to 2.7 V		−2		−2	mA
		V_{CC} = 3 V to 3.6 V		−6		−6	
		V_{CC} = 4.5 V to 5.5 V		−12		−12	
I_{OL}	Low-level output current	V_{CC} = 2 V		50		50	μA
		V_{CC} = 2.3 V to 2.7 V		2		2	mA
		V_{CC} = 3 V to 3.6 V		6		6	
		V_{CC} = 4.5 V to 5.5 V		12		12	
R_{ext}	External timing resistance	V_{CC} = 2 V	5k		5k		Ω
		$V_{CC} \geq$ 3 V	1k		1k		
C_{ext}	External timing capacitance		No restriction		No restriction		pF
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		1		1		ms/V
T_A	Operating free-air temperature		−55	125	−40	85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	SN54LV221A			SN74LV221A			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
V_{OH}		I_{OH} = −50 μA	2 V to 5.5 V	V_{CC}−0.1			V_{CC}−0.1			V
		I_{OH} = −2 mA	2.3 V	2			2			
		I_{OH} = −6 mA	3 V	2.48			2.48			
		I_{OH} = −12 mA	4.5 V	3.8			3.8			
V_{OL}		I_{OL} = 50 μA	2 V to 5.5 V			0.1			0.1	V
		I_{OL} = 2 mA	2.3 V			0.4			0.4	
		I_{OL} = 6 mA	3 V			0.44			0.44	
		I_{OL} = 12 mA	4.5 V			0.55			0.55	
I_I	R_{ext}/C_{ext}†	V_I = 5.5 V or GND	2 V to 5.5 V			±2.5			±2.5	μA
	$\overline{A}$, B, and $\overline{CLR}$	V_I = 5.5 V or GND	0			±1			±1	
			0 to 5.5 V			±1			±1	
I_{CC}	Quiescent	$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			20			20	μA
I_{CC}	Active state (per circuit)	$V_I = V_{CC}$ or GND, R_{ext}/C_{ext} = 0.5 V_{CC}	2.3 V			220			220	μA
			3 V			280			280	
			4.5 V			650			650	
			5.5 V			975			975	
I_{off}		V_I or V_O = 0 to 5.5 V	0						5	μA
C_i		$V_I = V_{CC}$ or GND	3.3 V		1.9			1.9		pF
			5 V		1.9			1.9		

† This test is performed with the terminal in the off-state condition.

timing requirements over recommended operating free-air temperature range, V_{CC} = 2.5 V ± 0.2 V (unless otherwise noted) (see Figure 1)

			T_A = 25°C		SN54LV221A		SN74LV221A		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration	$\overline{CLR}$	6		6.5		6.5		ns
		$\overline{A}$ or B trigger	6		6.5		6.5		

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

			T_A = 25°C		SN54LV221A		SN74LV221A		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration	$\overline{CLR}$	5		5		5		ns
		$\overline{A}$ or B trigger	5		5		5		

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

			T_A = 25°C		SN54LV221A		SN74LV221A		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration	$\overline{CLR}$	5		5		5		ns
		$\overline{A}$ or B trigger	5		5		5		

switching characteristics over recommended operating free-air temperature range, V_{CC} = 2.5 V ± 0.2 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	T_A = 25°C			SN54LV221A		SN74LV221A		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{pd}	$\overline{A}$ or B	Q or $\overline{Q}$	C_L = 15 pF		14.6*	31.4*	1*	37*	1	37	ns
	$\overline{CLR}$	Q or $\overline{Q}$			13.2*	25*	1*	29.5*	1	29.5	
	$\overline{CLR}$ trigger	Q or $\overline{Q}$			15.2*	33.4*	1*	39*	1	39	
t_{pd}	$\overline{A}$ or B	Q or $\overline{Q}$	C_L = 50 pF		16.7	36	1	42	1	42	ns
	$\overline{CLR}$	Q or $\overline{Q}$			15	32.8	1	34.5	1	34.5	
	$\overline{CLR}$ trigger	Q or $\overline{Q}$			17.4	38	1	44	1	44	
t_w†		Q or $\overline{Q}$	C_L = 50 pF, C_{ext} = 28 pF, R_{ext} = 2 kΩ		203	260		320		320	ns
			C_L = 50 pF, C_{ext} = 0.01 µF, R_{ext} = 10 kΩ	90	100	110	90	110	90	110	µs
			C_L = 50 pF, C_{ext} = 0.1 µF, R_{ext} = 10 kΩ	0.9	1	1.1	0.9	1.1	0.9	1.1	ms
Δt_w‡			C_L = 50 pF		±1						%

* On products compliant to MIL-PRF-38535, this parameter is not production tested.
† t_w = Pulse duration at Q and $\overline{Q}$ outputs
‡ Δt_w = Output pulse-duration variation (Q and $\overline{Q}$) between circuits in same package

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	T_A = 25°C			SN54LV221A		SN74LV221A		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{pd}	$\overline{A}$ or B	Q or $\overline{Q}$	C_L = 15 pF		10.2*	20.6*	1*	24*	1	24	ns
	$\overline{CLR}$	Q or $\overline{Q}$			9.3*	15.8*	1*	18.5*	1	18.5	
	$\overline{CLR}$ trigger	Q or $\overline{Q}$			10.6*	22.4*	1*	26*	1	26	
t_{pd}	$\overline{A}$ or B	Q or $\overline{Q}$	C_L = 50 pF		11.8	24.1	1	27.5	1	27.5	ns
	$\overline{CLR}$	Q or $\overline{Q}$			10.6	19.3	1	22	1	22	
	$\overline{CLR}$ trigger	Q or $\overline{Q}$			12.3	25.9	1	29.5	1	29.5	
t_w†		Q or $\overline{Q}$	C_L = 50 pF, C_{ext} = 28 pF, R_{ext} = 2 kΩ		186	240		300		300	ns
			C_L = 50 pF, C_{ext} = 0.01 µF, R_{ext} = 10 kΩ	90	100	110	90	110	90	110	µs
			C_L = 50 pF, C_{ext} = 0.1 µF, R_{ext} = 10 kΩ	0.9	1	1.1	0.9	1.1	0.9	1.1	ms
Δt_w‡			C_L = 50 pF		±1						%

* On products compliant to MIL-PRF-38535, this parameter is not production tested.
† t_w = Pulse duration at Q and $\overline{Q}$ outputs
‡ Δt_w = Output pulse-duration variation (Q and $\overline{Q}$) between circuits in same package

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

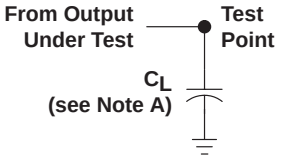
PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	T_A = 25°C			SN54LV221A		SN74LV221A		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{pd}	$\overline{A}$ or B	Q or $\overline{Q}$	C_L = 15 pF		7.1*	12*	1*	14*	1	14	ns
	$\overline{CLR}$	Q or $\overline{Q}$			6.5*	9.4*	1*	11*	1	11	
	$\overline{CLR}$ trigger	Q or $\overline{Q}$			7.3*	12.9*	1*	15*	1	15	
t_{pd}	$\overline{A}$ or B	Q or $\overline{Q}$	C_L = 50 pF		8.2	14	1	16	1	16	ns
	$\overline{CLR}$	Q or $\overline{Q}$			7.4	11.4	1	13	1	13	
	$\overline{CLR}$ trigger	Q or $\overline{Q}$			8.6	14.9	1	17	1	17	
t_w†		Q or $\overline{Q}$	C_L = 50 pF, C_{ext} = 28 pF, R_{ext} = 2 kΩ		171	200		240		240	ns
			C_L = 50 pF, C_{ext} = 0.01 µF, R_{ext} = 10 kΩ	90	100	110	90	110	90	110	µs
			C_L = 50 pF, C_{ext} = 0.1 µF, R_{ext} = 10 kΩ	0.9	1	1.1	0.9	1.1	0.9	1.1	ms
Δt_w‡			C_L = 50 pF		±1						%

* On products compliant to MIL-PRF-38535, this parameter is not production tested.
† t_w = Pulse duration at Q and $\overline{Q}$ outputs
‡ Δt_w = Output pulse-duration variation (Q and $\overline{Q}$) between circuits in same package

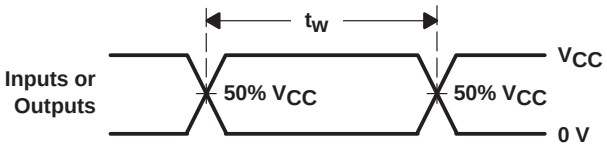
operating characteristics, T_A = 25°C

PARAMETER		TEST CONDITIONS	V_{CC}	TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 10 MHz	3.3 V	50	pF
			5 V	51	

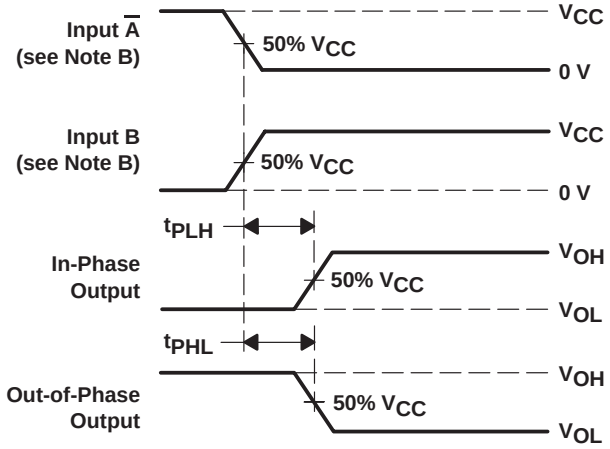
PARAMETER MEASUREMENT INFORMATION



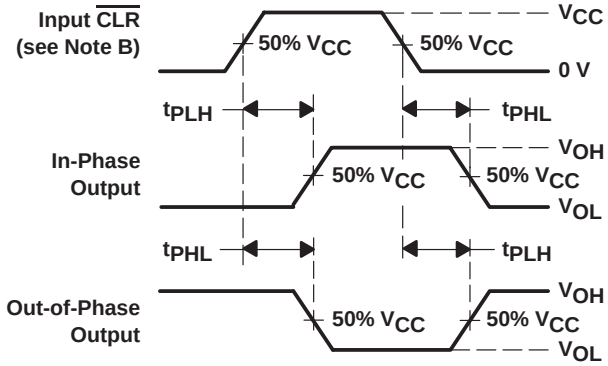
LOAD CIRCUIT



VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
DELAY TIMES



VOLTAGE WAVEFORMS
DELAY TIMES

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. The outputs are measured one at a time, with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

APPLICATION INFORMATION

caution in use

To prevent malfunctions due to noise, connect a high-frequency capacitor between V_{CC} and GND, and keep the wiring between the external components and C_{ext} and R_{ext}/C_{ext} terminals as short as possible.

power-down considerations

Large values of C_{ext} can cause problems when powering down the ’LV221A because of the amount of energy stored in the capacitor. When a system containing this device is powered down, the capacitor can discharge from V_{CC} through the protection diodes at pin 2 or pin 14. Current through the input protection diodes must be limited to 30 mA; therefore, the turn-off time of the V_{CC} power supply must not be faster than $t = V_{CC} \times C_{ext}/30$ mA. For example, if V_{CC} = 5 V and C_{ext} = 15 pF, the V_{CC} supply must turn off no faster than $t = (5\ V) \times (15\ pF)/30\ mA = 2.5$ ns. Usually, this is not a problem because power supplies are heavily filtered and cannot discharge at this rate. When a more rapid decrease of V_{CC} to zero occurs, the ’LV221A can sustain damage. To avoid this possibility, use external clamping diodes.

output pulse duration

The output pulse duration, t_w, is determined primarily by the values of the external capacitance (C_T) and timing resistance (R_T). The timing components are connected as shown in Figure 2.

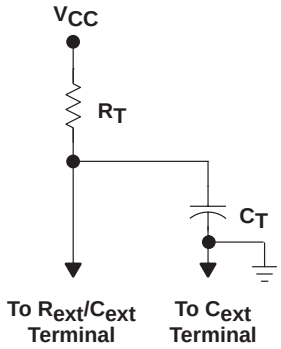


Figure 2. Timing-Component Connections

The pulse duration is given by:

$$t_w = K \times R_T \times C_T \quad (1)$$

if C_T is ≥ 1000 pF, K = 1.0

or

if C_T is < 1000 pF, K can be determined from Figure 7

where:

t_w = pulse duration in ns
R_T = external timing resistance in kΩ
C_T = external capacitance in pF
K = multiplier factor

Equation 1 and Figure 3 or 4 can be used to determine values for pulse duration, external resistance, and external capacitance.

APPLICATION INFORMATION†

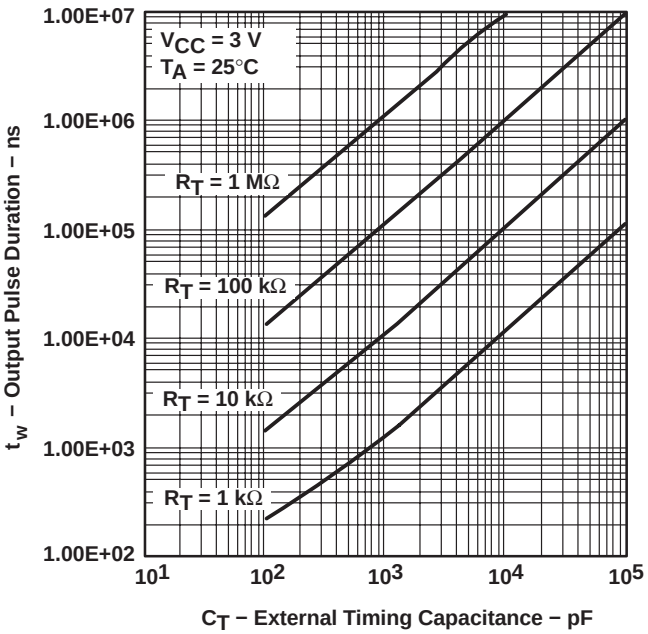


Figure 3

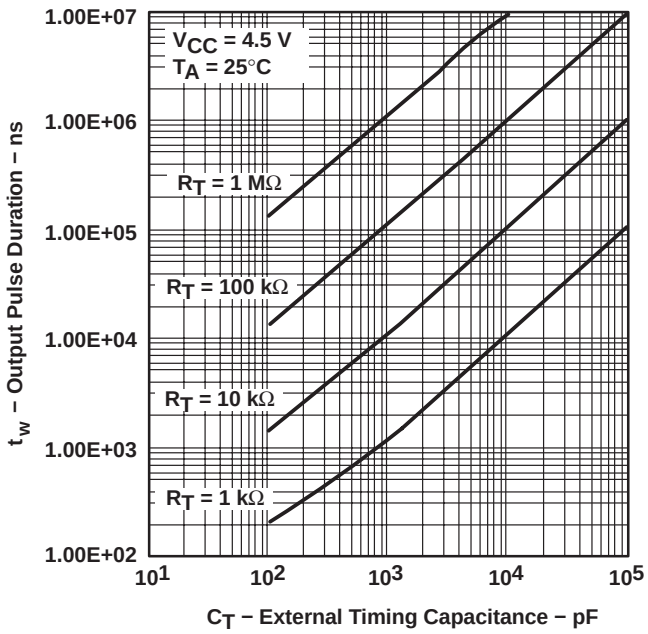


Figure 4

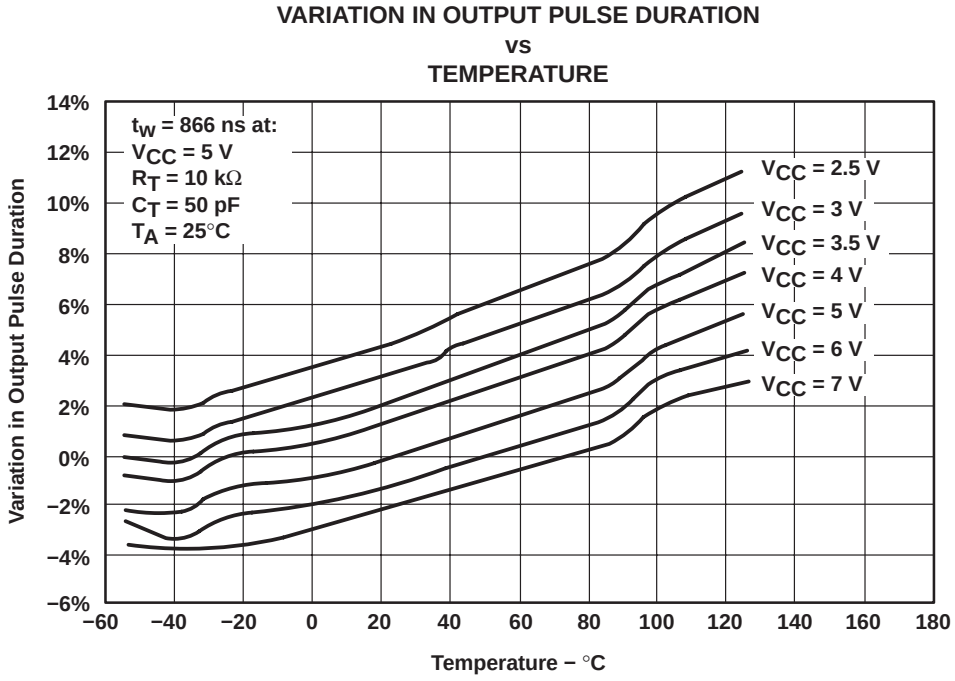


Figure 5

† Operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied.

APPLICATION INFORMATION†

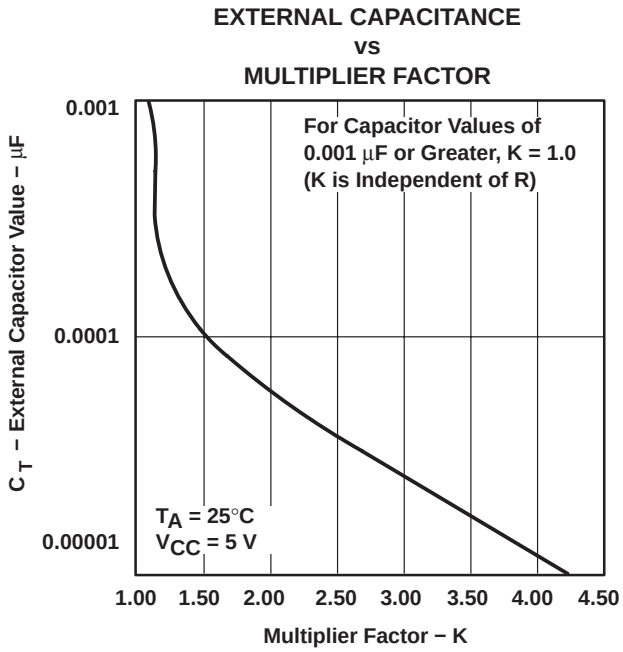


Figure 6

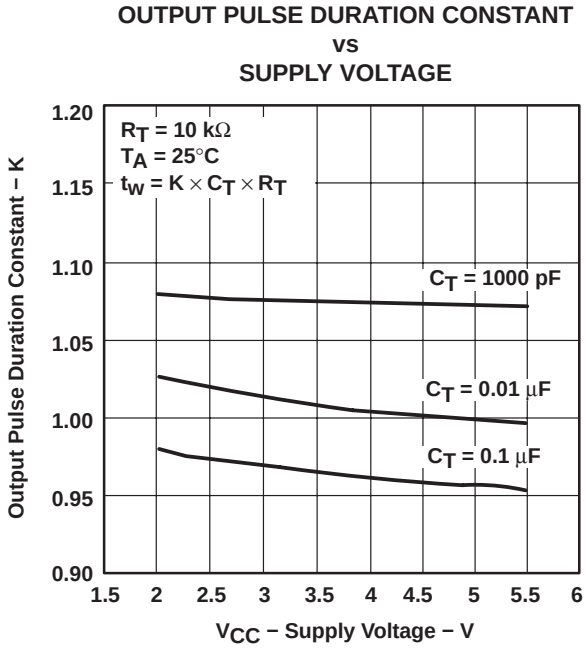


Figure 7

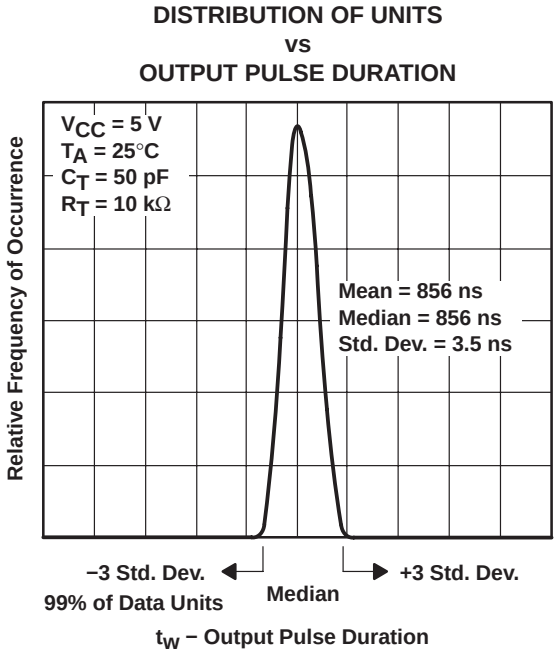


Figure 8

† Operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LV221AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV221A	Samples
SN74LV221ADG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV221A	Samples
SN74LV221ADGVR	ACTIVE	TVSOP	DGV	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV221A	Samples
SN74LV221ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV221A	Samples
SN74LV221ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	74LV221A	Samples
SN74LV221APW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV221A	Samples
SN74LV221APWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV221A	Samples
SN74LV221APWT	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV221A	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

OTHER QUALIFIED VERSIONS OF SN74LV221A :

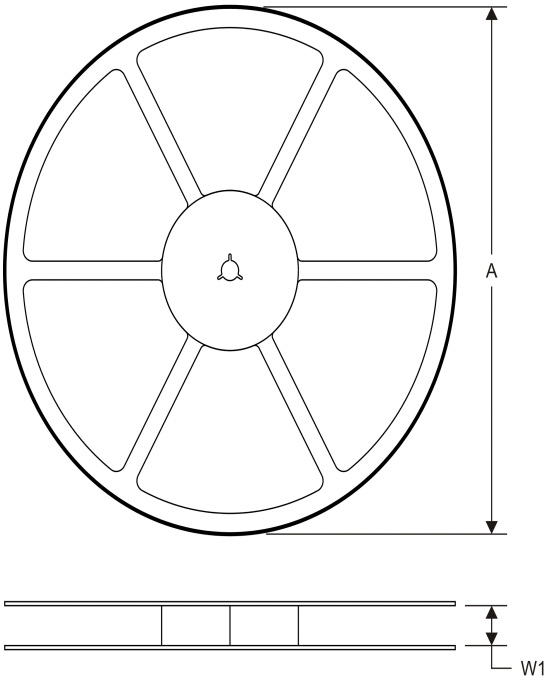
- Automotive: SN74LV221A-Q1

NOTE: Qualified Version Definitions:

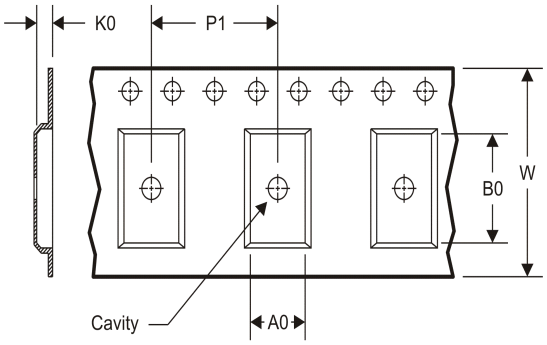
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



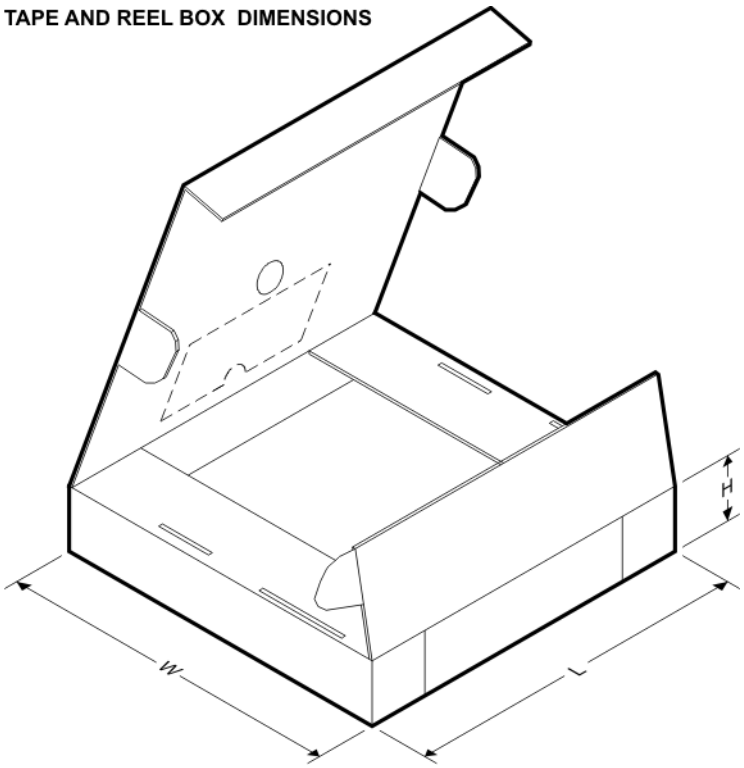
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV221ADGVR	TVSOP	DGV	16	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74LV221ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LV221ANSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LV221APWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV221APWT	TSSOP	PW	16	250	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS

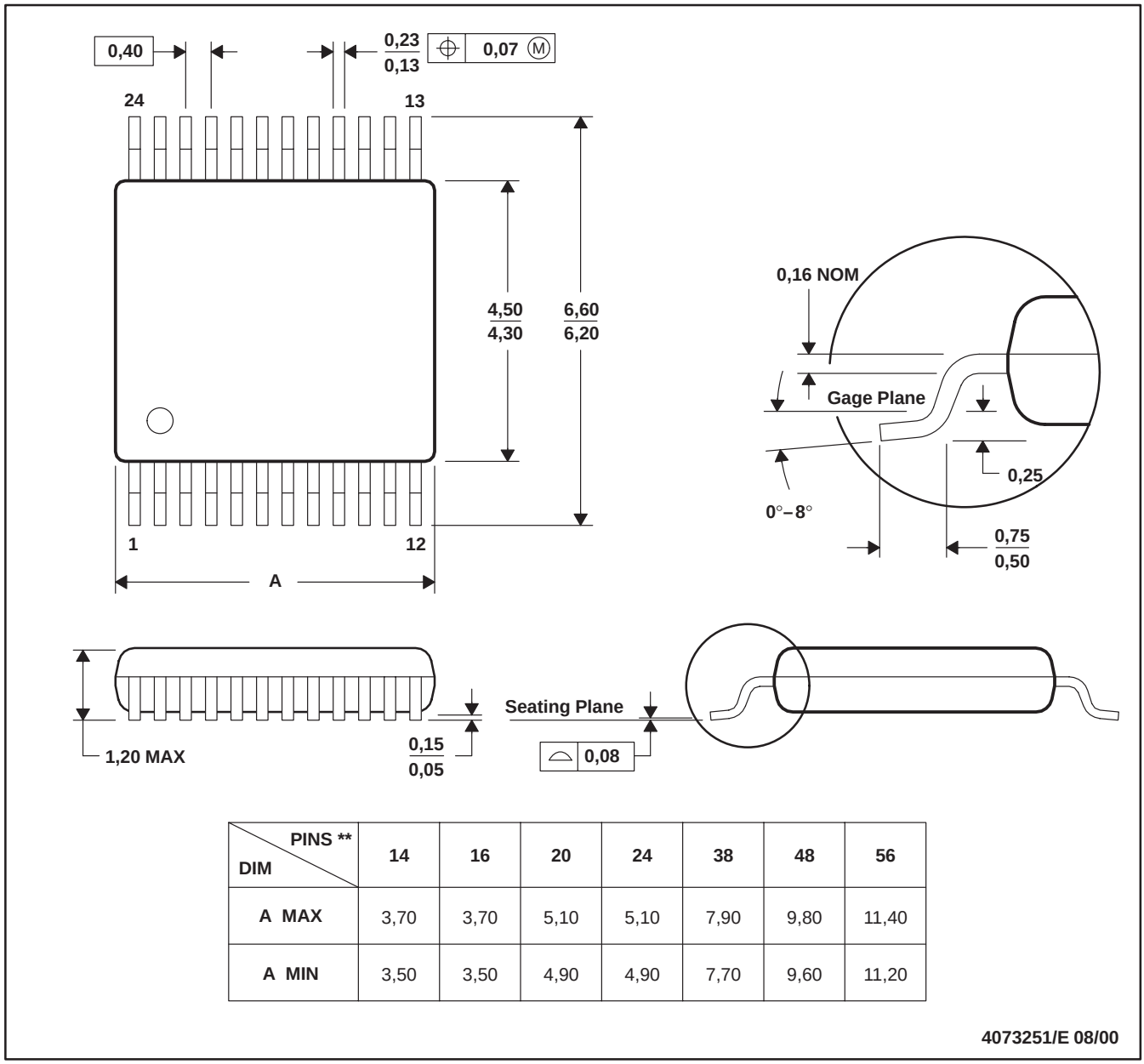


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV221ADGVR	TVSOP	DGV	16	2000	367.0	367.0	35.0
SN74LV221ADR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LV221ANSR	SO	NS	16	2000	367.0	367.0	38.0
SN74LV221APWR	TSSOP	PW	16	2000	367.0	367.0	35.0
SN74LV221APWT	TSSOP	PW	16	250	367.0	367.0	35.0

DGV (R-PDSO-G)** **PLASTIC SMALL-OUTLINE**

24 PINS SHOWN

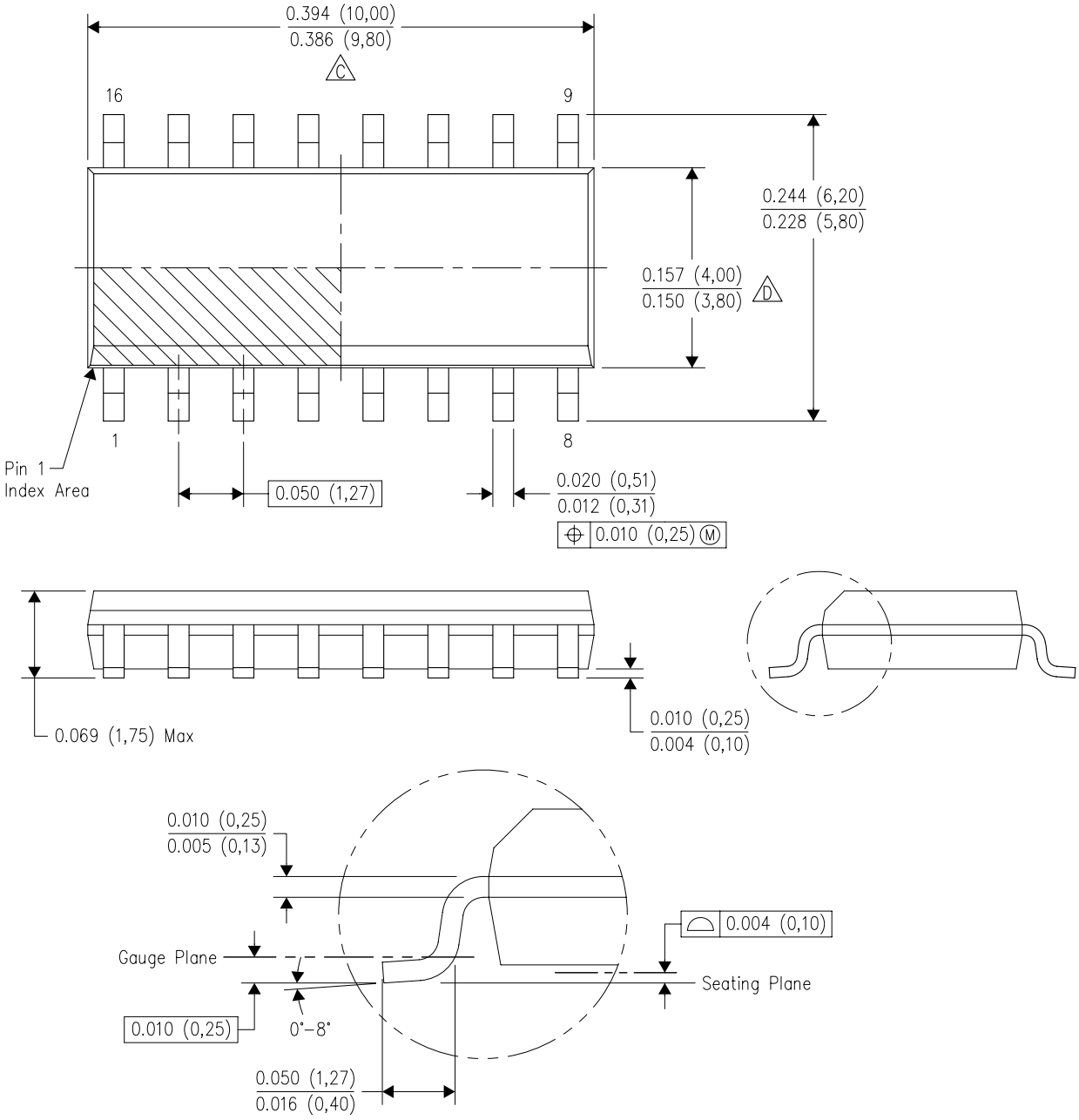


DIM \ PINS **	14	16	20	24	38	48	56
A MAX	3,70	3,70	5,10	5,10	7,90	9,80	11,40
A MIN	3,50	3,50	4,90	4,90	7,70	9,60	11,20

4073251/E 08/00

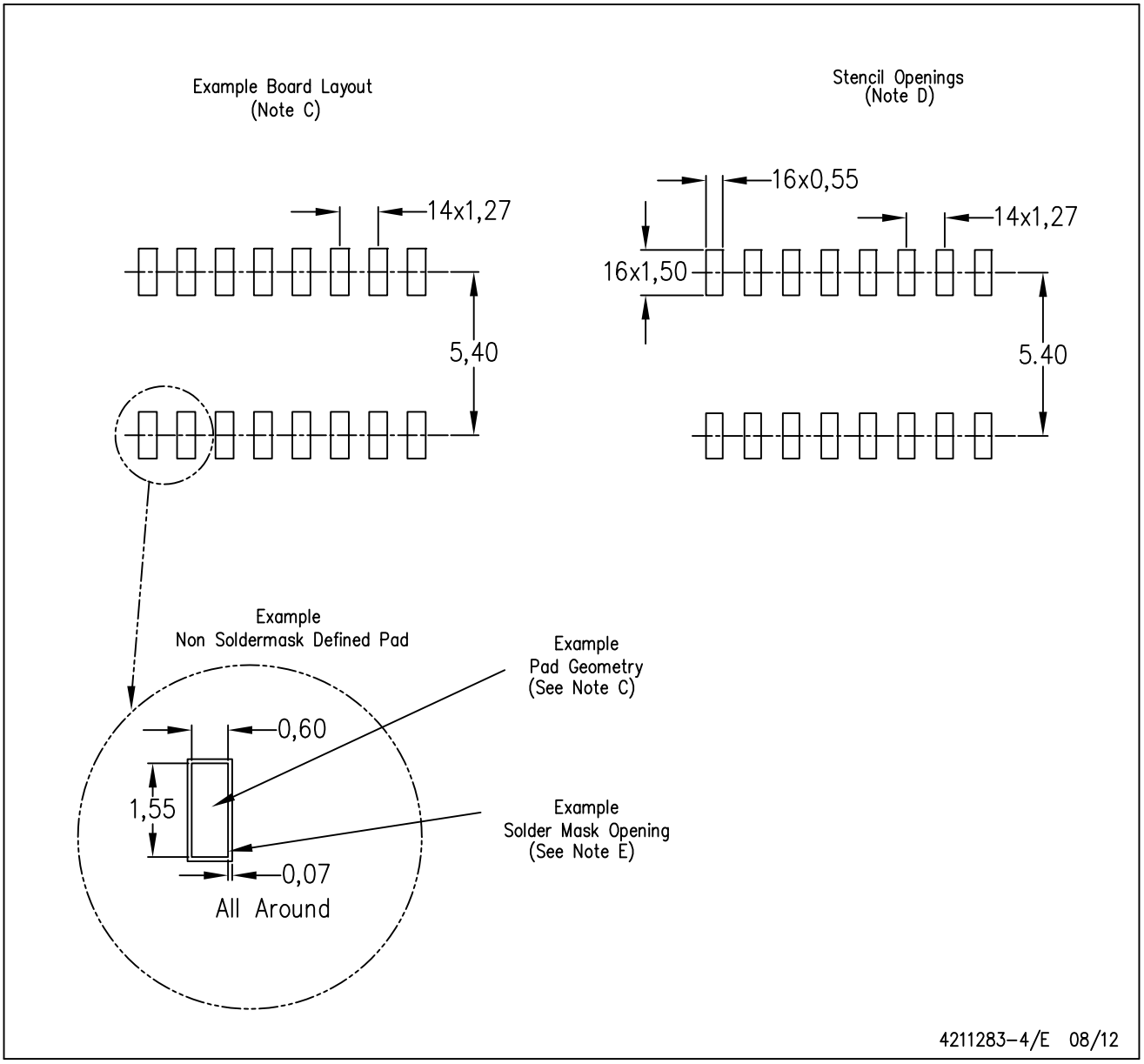
NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
D. Falls within JEDEC: 24/48 Pins – MO-153
14/16/20/56 Pins – MO-194

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



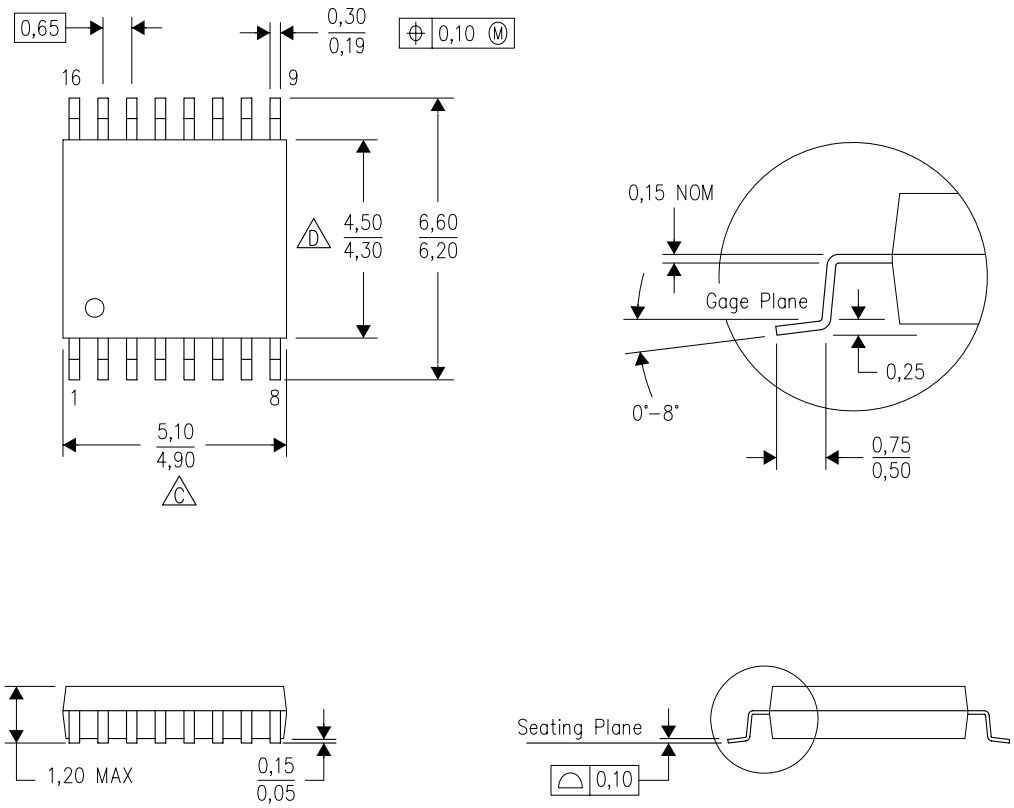
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AC.

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

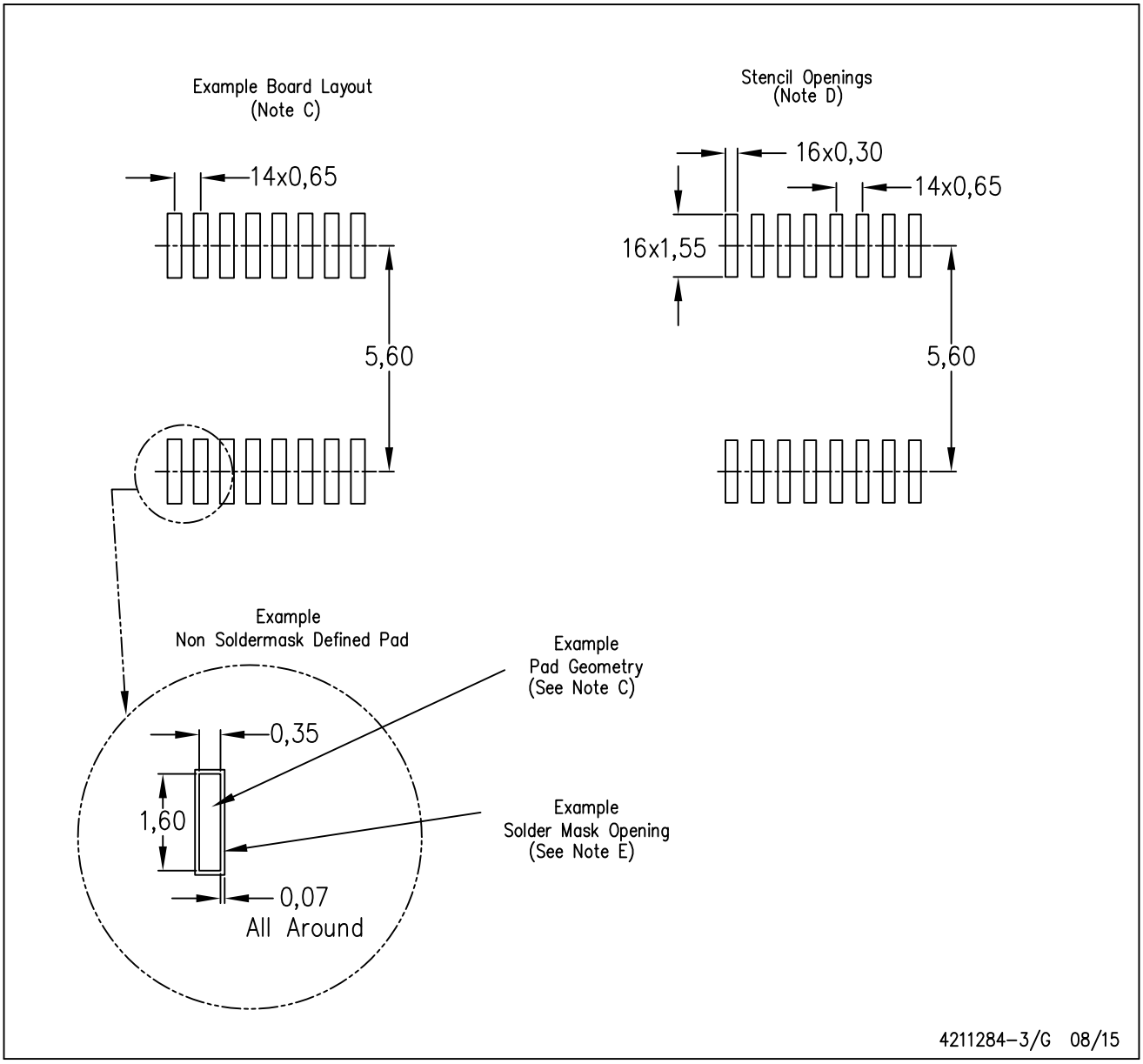
PW (R–PDSO–G16) PLASTIC SMALL OUTLINE



4040064–4/G 02/11

NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
E. Falls within JEDEC MO–153

PW (R–PDSO–G16) PLASTIC SMALL OUTLINE

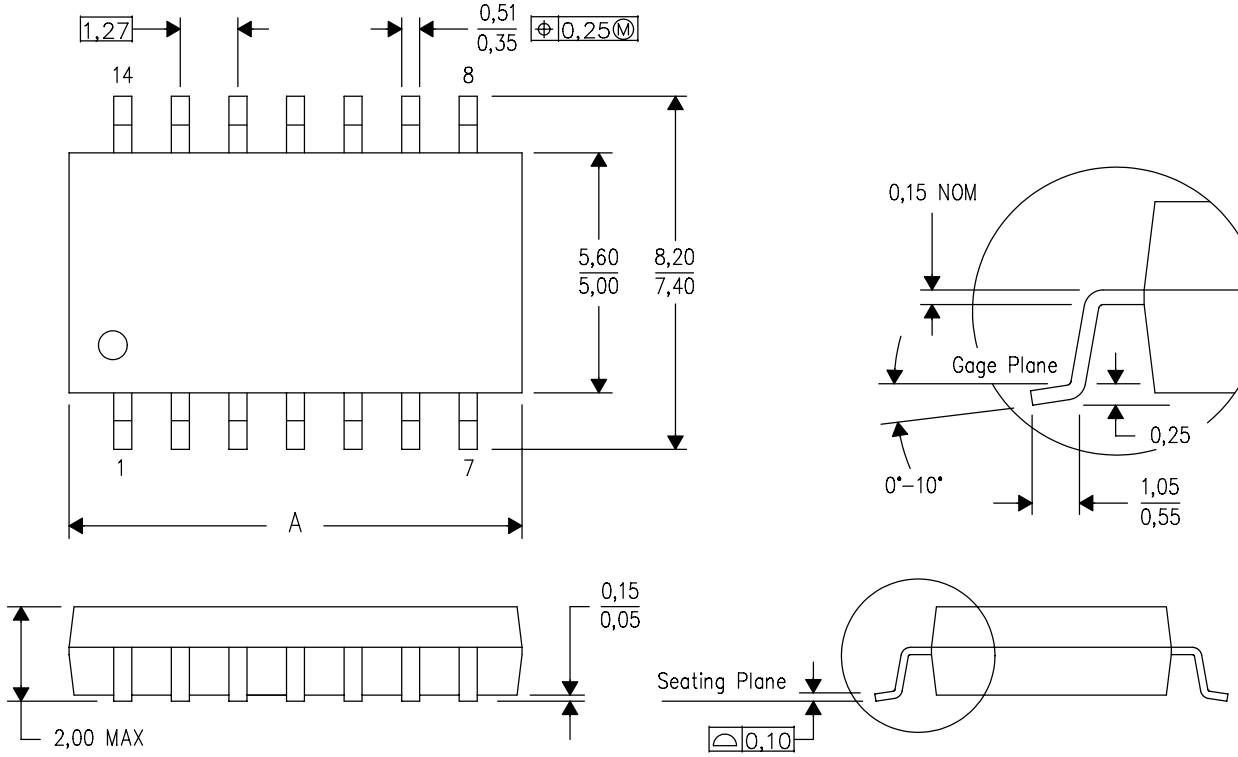


NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as “components”) are sold subject to TI’s terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI’s terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers’ products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers’ products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI’s goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or “enhanced plastic” are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have ***not*** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products		**Applications**	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Applications Processors	www.ti.com/omap	**TI E2E Community**	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconnectivity		

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265